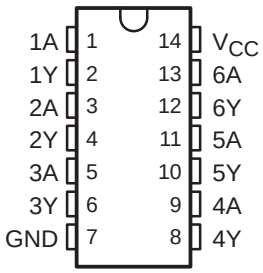
The SN5405 is obsolete and no longer is supplied.

SN54LS05, SN54S05 SN7405, SN74LS05, SN74S05 HEX INVERTERS WITH OPEN-COLLECTOR OUTPUTS

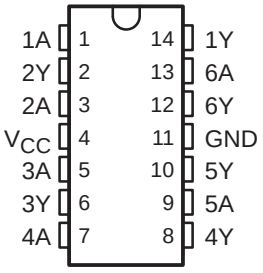
SDLS030A − DECEMBER 1983 − REVISED NOVEMBER 2003

- **Package Options Include Plastic Small-Outline (D, NS), Shrink Small-Outline (DB), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) DIPs**
- **Dependable Texas Instrument Quality and Reliability**

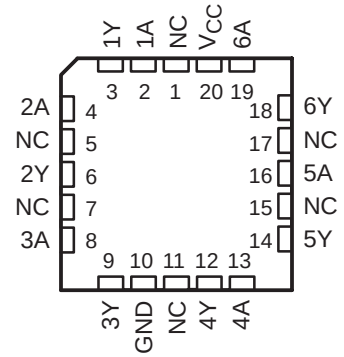
SN5405, SN54LS05, SN54S05 . . . J PACKAGE
SN7405 . . . N PACKAGE
SN74LS05 . . . D, DB, N, OR NS PACKAGE
SN74S05 . . . D, N, OR NS PACKAGE
(TOP VIEW)



SN54LS05, SN54S05 . . . W PACKAGE
(TOP VIEW)



SN54LS05, SN54S05 . . . FK PACKAGE
(TOP VIEW)



NC − No internal connection

description/ordering information

These devices contain six independent inverters. To perform correctly, the open-collector outputs require pullup resistors. These devices may be connected to other open-collector outputs to implement active-low wired-OR or active-high wire-AND functions. Open-collector devices often are used to generate high V_{OH} levels.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP − N	Tube	SN7405N	SN7405N
			SN74LS05N	SN74LS05N
			SN74S05N	SN74S05N
	SOIC − D	Tube	SN74LS05D	LS05
		Tape and reel	SN74LS05DR	
		Tube	SN74S05D	S05
		Tape and reel	SN74S05DR	
	SOP − NS	Tape and reel	SN74LS05NSR	74LS05
			SN74S05NSR	74S05
	SSOP − DB	Tape and reel	SN74LS05DBR	LS05
−55°C to 125°C	CDIP − J	Tube	SNJ54LS05J	SNJ54LS05J
			SNJ54S05J	SNJ54S05J
	CDIP − W	Tube	SNJ54LS05W	SNJ54LS05W
			SNJ54S05W	SNJ54S05W
	LCCC − FK	Tube	SNJ54LS05FK	SNJ54LS05FK
			SNJ54S05FK	SNJ54S05FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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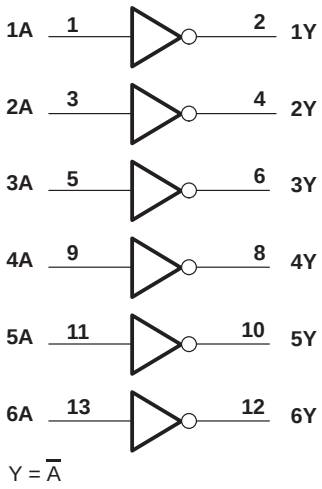
On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

The SN5405 is obsolete and no longer is supplied.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
H	L
L	H

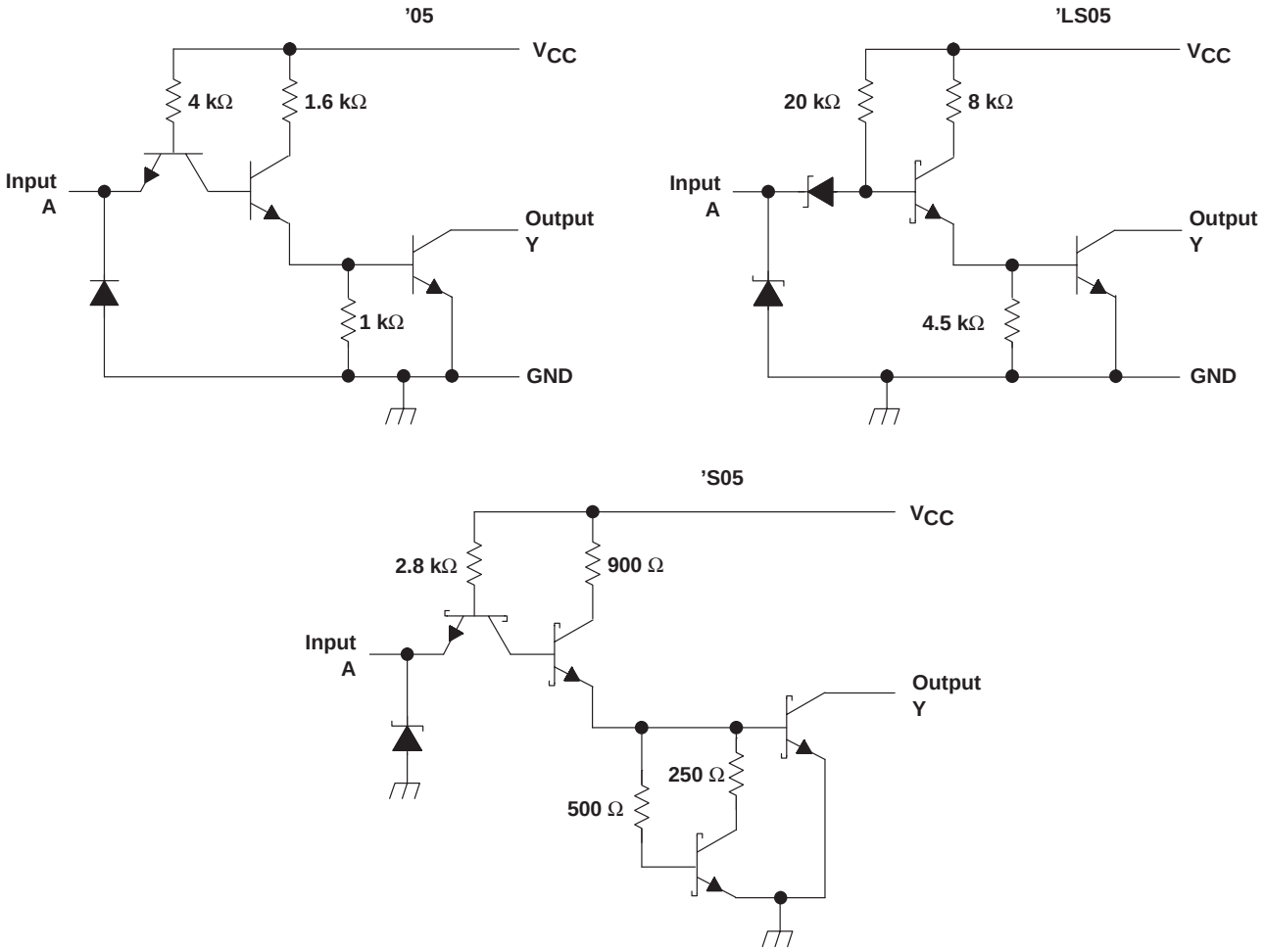
logic diagram (positive logic)



$Y = \overline{A}$

Pin numbers shown are for the D, DB, J, N, and NS packages.

schematic (each inverter)



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1): '05, 'LS05, 'S05 . . . . . 7 V
Input voltage, V_I: '05, 'S05 . . . . . 5.5 V
'LS05 . . . . . 7 V
Off-state output voltage, V_O . . . . . 7 V
Package thermal impedance, θ_{JA} (see Note 2): D package . . . . . 86°C/W
DB package . . . . . 96°C/W
N package . . . . . 80°C/W
NS package . . . . . 76°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values are with respect to network ground terminal.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

The SN5405 is obsolete and no longer is supplied.

recommended operating conditions

		SN5405			SN7405			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			16			16	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			SN5405			SN7405			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −12 mA				−1.5			−1.5	V
I_{OH}	V_{CC} = MIN,	V_{OH} = 5.5 V	V_{IL} = 0.8 V						0.25	mA
			V_{IL} = 0.7 V			0.25				
V_{OL}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OL} = 16 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.4 V				40			40	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V				−1.6			−1.6	mA
I_{CCH}	V_{CC} = MAX,	V_I = 0 V			6	12		6	12	mA
I_{CCL}	V_{CC} = MAX,	V_I = 4.5 V			18	33		18	33	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A	Y	R_L = 4 kΩ	C_L = 15 pF		40	55	ns
t_{PHL}			R_L = 400 Ω			8	15	

recommended operating conditions

		SN54LS05			SN74LS05			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			4			8	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†			SN54LS05			SN74LS05			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −18 mA				−1.5			−1.5	V
I_{OH}	V_{CC} = MIN,	V_{IL} = MAX,	V_{OH} = 5.5 V			0.1			0.1	mA
V_{OL}	V_{CC} = MIN,	V_{IH} = 2 V	I_{OL} = 4 mA		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA					0.35	0.5	
I_I	V_{CC} = MAX,	V_I = 7 V				0.1			0.1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.7 V				20			20	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.4 V				−0.4			−0.4	mA
I_{CCH}	V_{CC} = MAX,	V_I = 0 V			1.2	2.4		1.2	2.4	mA
I_{CCL}	V_{CC} = MAX,	V_I = 4.5 V			3.6	6.6		3.6	6.6	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	A	Y	R_L = 2 kΩ, C_L = 15 pF		17	32	ns
t_{PHL}					15	28	

The SN5405 is obsolete and no longer is supplied.

recommended operating conditions

		SN54S05			SN74S05			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

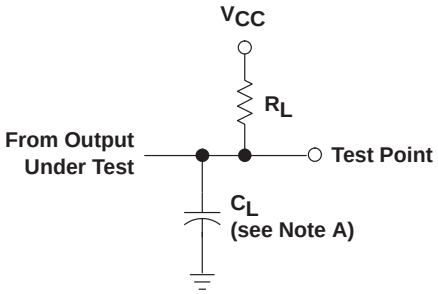
PARAMETER	TEST CONDITIONS†			SN54S05			SN74S05			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −18 mA				−1.2			−1.2	V
I_{OH}	V_{CC} = MIN,	V_{OH} = 5.5 V	V_{IL} = 0.8 V						0.25	mA
			V_{IL} = 0.7 V			0.25				
V_{OL}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OL} = 20 mA			0.5			0.5	V
I_I	V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.7 V				50			50	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.5 V				−2			−2	mA
I_{CCH}	V_{CC} = MAX,	V_I = 0 V			9	19.8		9	19.8	mA
I_{CCL}	V_{CC} = MAX,	V_I = 4.5 V			30	54		30	54	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

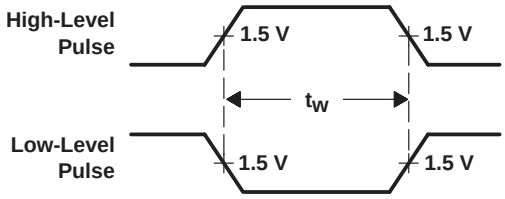
switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	A	Y	R_L = 280 Ω	C_L = 15 pF	2	5	7.5	ns
t_{PHL}					2	4.5	7	
t_{PLH}				C_L = 50 pF		7.5		ns
t_{PHL}						7		

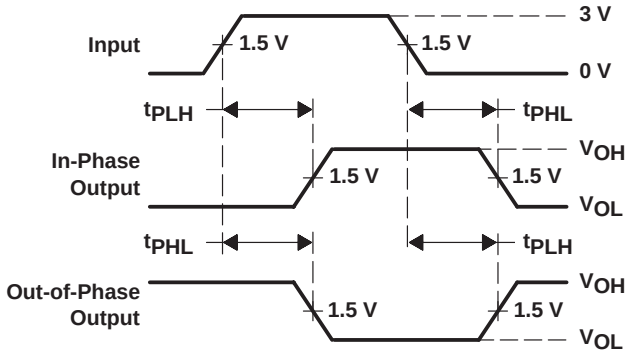
PARAMETER MEASUREMENT INFORMATION
SERIES 54/74 AND 54S/74S DEVICES



LOAD CIRCUIT



VOLTAGE WAVEFORMS
PULSE WIDTHS



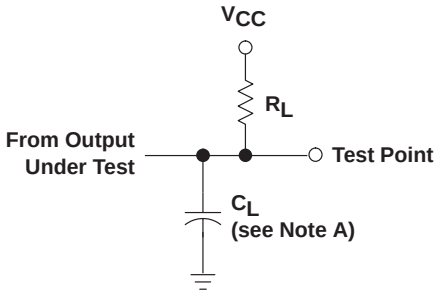
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, and:
For Series 54/74, t_r ≤ 7 ns, t_f ≤ 7 ns.
For Series 54S/74S, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one input transition per measurement.

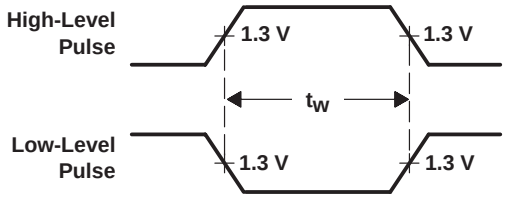
Figure 1. Load Circuit and Voltage Waveforms

The SN5405 is obsolete and no longer is supplied.

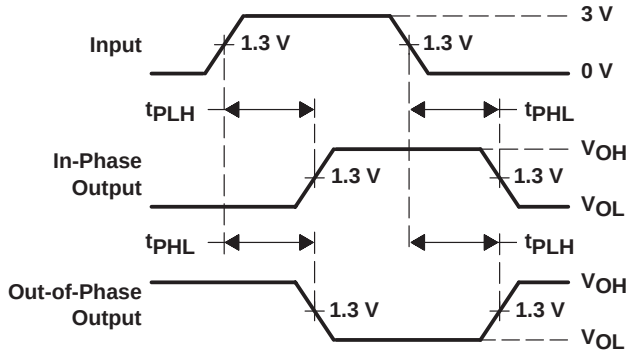
PARAMETER MEASUREMENT INFORMATION
SERIES 54LS/74LS DEVICES



LOAD CIRCUIT



VOLTAGE WAVEFORMS
PULSE WIDTHS



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 1.5 ns, t_f ≤ 2.6 ns.
D. The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
JM38510/07003BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/07004BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS05J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S05J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7405D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7405DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN7405N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7405N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7405NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS05D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS05DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LS05DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS05DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS05DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS05DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS05DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS05N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS05N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS05NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS05NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS05NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S05D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S05DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S05DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S05DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S05N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S05N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S05NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S05NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74S05NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS05FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS05J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS05W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S05FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S05J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S05W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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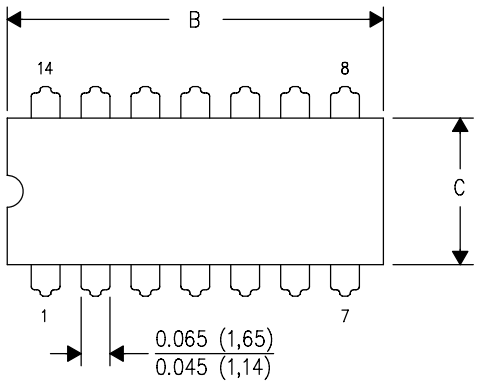
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

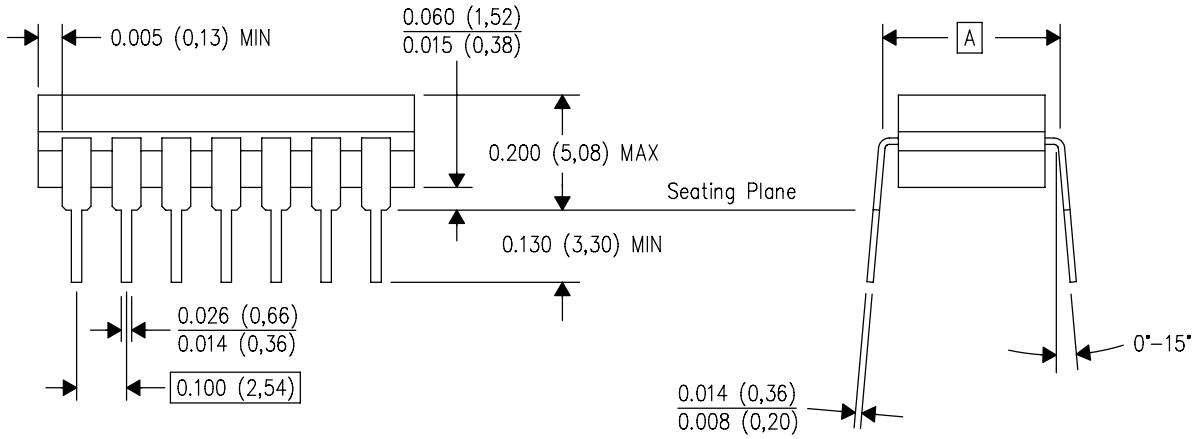
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



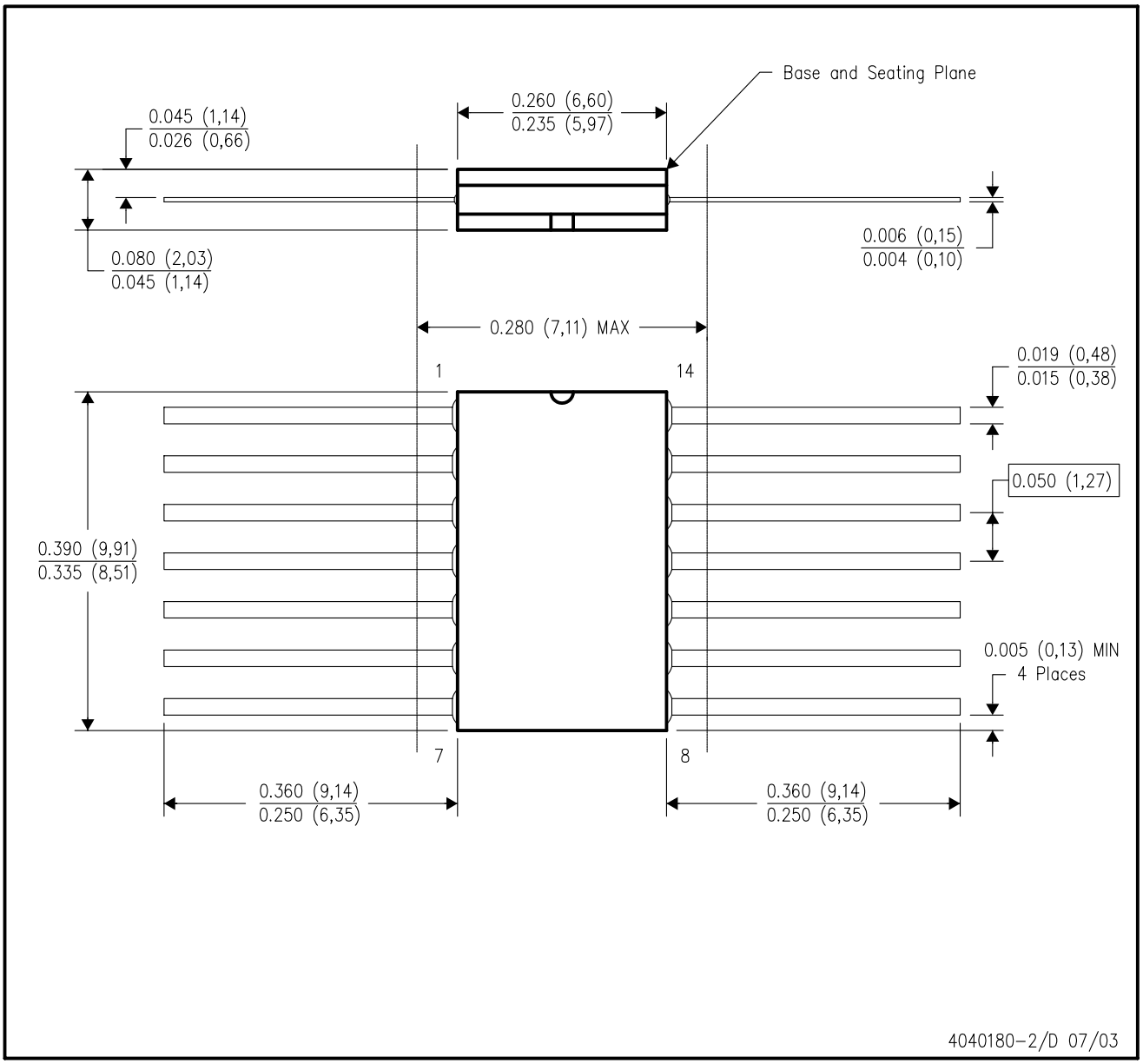
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

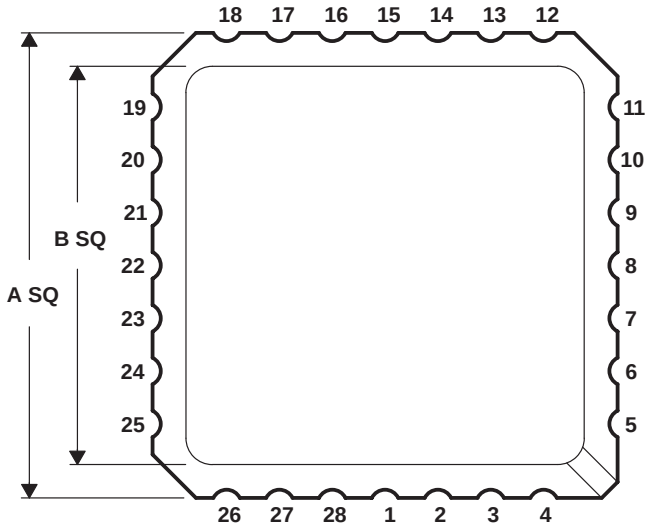
W (R–GDFP–F14) CERAMIC DUAL FLATPACK



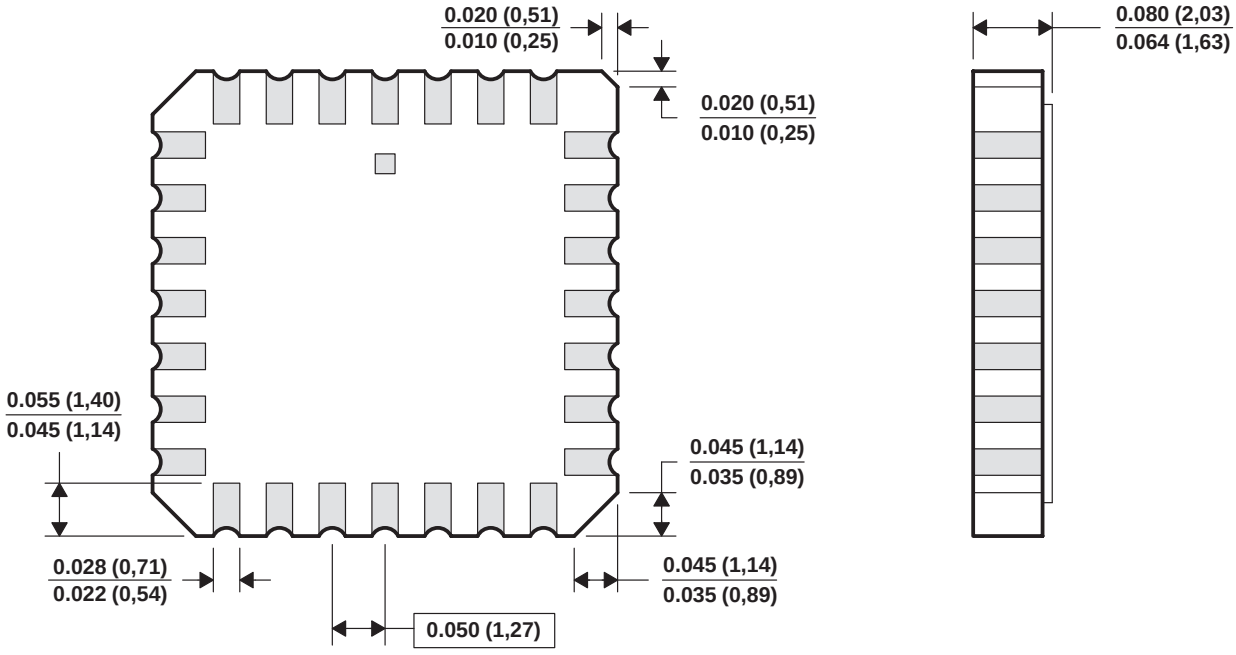
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



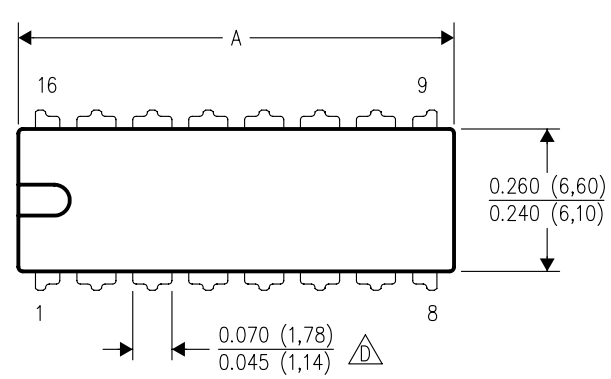
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

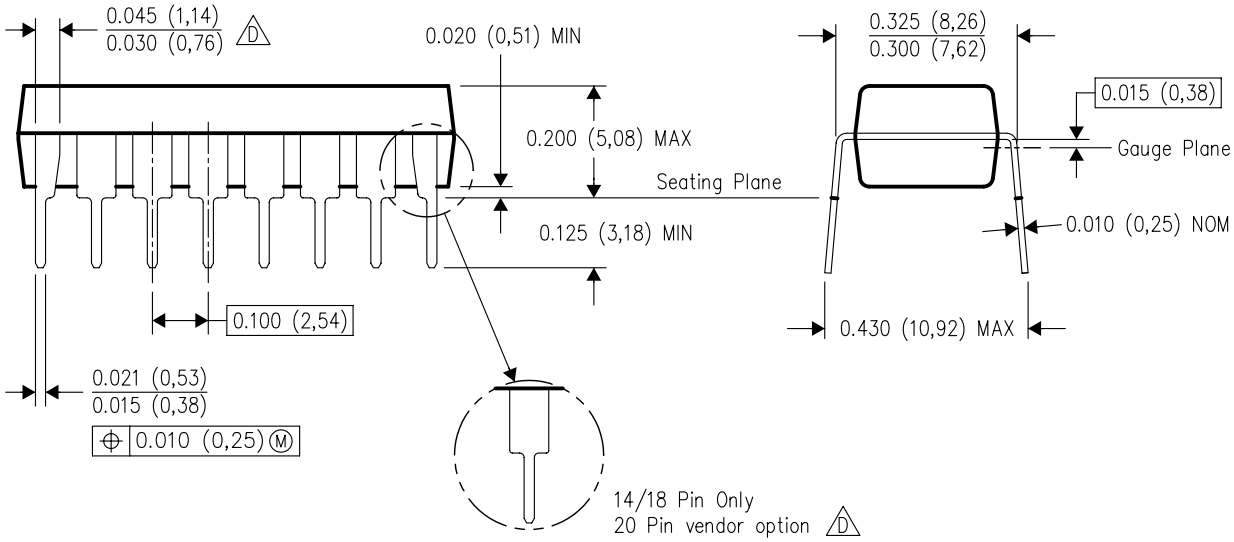
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



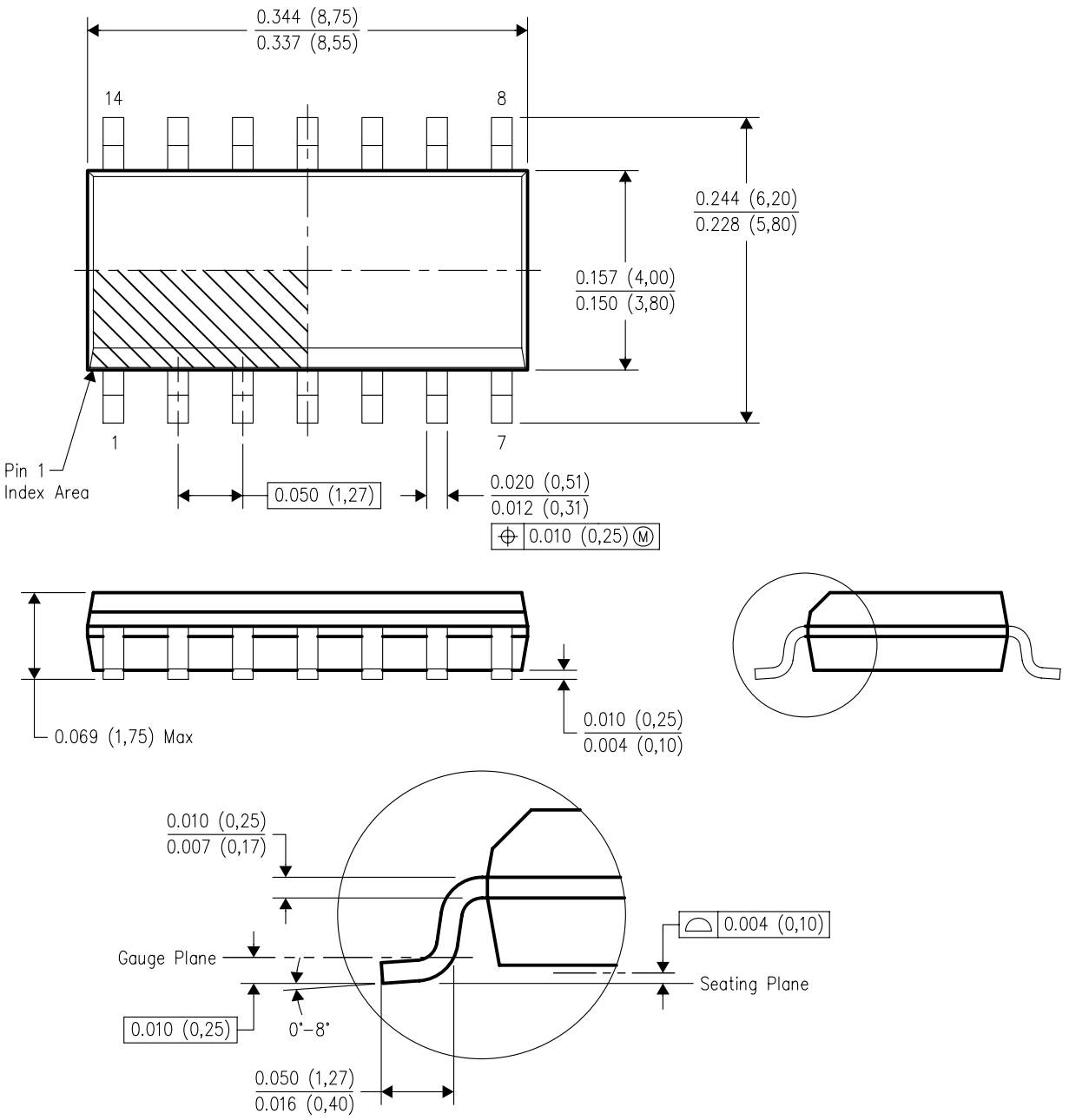
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE

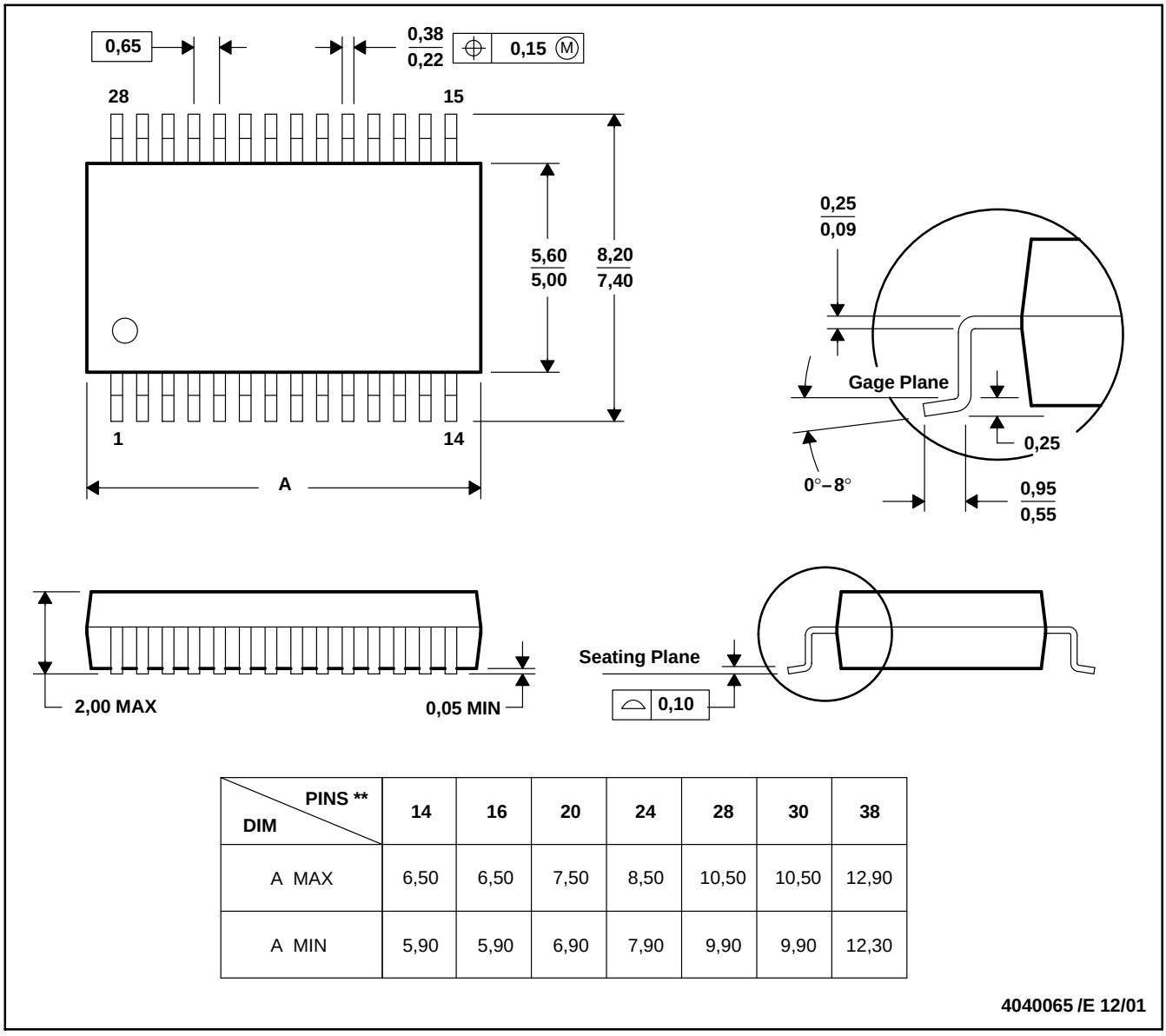


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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